What is claimed is:

- 1. A component mounter for picking up a component from a component feeder carriage and mounting the component on a board using a transfer head, said component mounter comprising:
- 5 (a) a positioner for relatively positioning said board with respect to said transfer head;
 - (b) a first memory for storing a position measurement result of solder printed on an electrode on said board;
 - (c) a calculator for calculating mounting coordinates for mounting the component using said transfer head based on said measurement result; and
 - (d) a controller for driving said positioner based on said mounting coordinates.
- 2. The component mounter as defined in Claim 1 further comprising a
 second memory for storing said mounting coordinates.
 - 3. The component mounter as defined in Claim 1, wherein said measurement result is a result of measurement performed by a measuring apparatus installed in the component mounter.

20

10

4. The component mounter as defined in Claim 1, wherein said measurement result is a result of measurement performed by a testing function installed in a screen printer for printing solder on the electrode on the board.

5. The component mounter as defined in Claim 1, wherein said position measurement result is a result of measurement performed by a separate appearance inspection device other than the component mounter.

5

10

- 6. A method for picking up a component from a component feeder carriage and mounting the component on a board using a transfer head, said method comprising:
- (a) storing a position measurement result of solder printed on an electrode on said board;
- (b) calculating mounting coordinates for mounting the component by said transfer head based on said measurement result; and
- (c) controlling a positioner for relatively positioning said board with respect to said transfer head based on said mounting coordinates.
- 7. The method as defined in Claim 6, further comprising:
 recognizing a position of said board by a recognition mark on said
 board; and
 obtaining image data for the electrode on said board.
- 8. The method as defined in Claim 7, further comprising the step of measuring a printing position of solder printed on said electrode as relative coordinates with respect to the recognition mark on said board based on said image data.